Electrical Characterization of Packages for Use with GaAs MMIC Amplifiers

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A test methodology will be presented which combines the advantages of on-wafer RF probing with a TRL calibration to create a completely de-embeddable, novel "test fixture" capable of electrically characterizing most any style package or device. This scheme has been used to characterize many of the currently available microwave packages in order to identify appropriate packages for our MMIC amplifier products which cover frequencies up to 12 GHz. In addition, the technique has been employed to characterize injection molded plastic packages and to evaluate non-probeable MMICs.

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